

PART INFORMATION		
Mfg Item Number		MPXAZ6115A6U
Mfg Item Name		SMALL OUTLINE SMT
SUPPLIER		
Company Name		Freescale Semiconductor Inc
Company Unique ID		14-141-7928
Response Date		2016-03-17
Response Document ID		0870A1.23
Contact Name		Freescale Semiconductor Inc
Contact Title		Product Technical Support
Contact Phone		1-800-521-6274
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Authorized Representative		Daniel Binyon
Representative Title		EPP Customer Response
Representative Phone		512-895-3406
Representative Email		eppanlst@freescale.com
URL for Additional Information		www.freescale.com
DECLARATION		
EU RoHS		Yes
Pb Free		No
HalogenFree		No
Plating Indicator		
EU RoHS Exemption(s)		7c-I
MANUFACTURING		
Mfg Item Number		MPXAZ6115A6U
Mfg Item Name		SMALL OUTLINE SMT
Version		ALL
Weight		1.042500
UoM		g
Unit Volume		EACH
J-STD-020 MSL Rating		
Peak Processing Temperature		245 C
Max Time at Peak Temperature		30 seconds
Number of Processing Cycles		3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Non-Conductive Epoxy/Adhesive	0.0027						g					
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Silicone gum	67762-04-1		0.00002787	g	10324	1.0324		26	0.0026
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and Silicones, di-Me, Me vinyl, vinyl group-terminated	68083-18-1		0.00033186	g	122911	12.2911		318	0.0318
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	68083-19-2		0.00106195	g	383313	38.3313		1018	0.1018
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Proprietary Material-Other siloxanes and silicones	-		0.00059735	g	221236	22.1236		572	0.0572
Non-Conductive Epoxy/Adhesive		Glass	D4 and HMDZ treated Silicon Dioxide	68937-51-9		0.00039823	g	147493	14.7493		391	0.0391
Non-Conductive Epoxy/Adhesive		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.00025221	g	93412	9.3412		241	0.0241
Non-Conductive Epoxy/Adhesive		Metals	Titanium (IV) Oxide	13463-67-7		0.00003053	g	11308	1.1308		29	0.0029
Copper Lead Frame	0.7789						g					
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.42963502	g	551592	55.1592		412136	41.2136
Copper Lead Frame		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.01649243	g	21174	2.1174		15820	1.582
Copper Lead Frame		Metals	Gold, metal	7440-57-8		0.00061611	g	791	0.0791		590	0.059
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00036219	g	465	0.0465		347	0.0347
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.01035625	g	13296	1.3296		9034	0.9904
Copper Lead Frame		Nickel (external applications only)	Nickel	7440-02-0		0.00646278	g	8323	0.8323		6218	0.6218
Copper Lead Frame		Metals	Palladium, metal	7440-05-3		0.00031779	g	408	0.0408		304	0.0304
Copper Lead Frame		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6		0.0991859	g	127341	12.7341		95142	9.5142
Copper Lead Frame		Glass	Fibrous-glass-wool	65907-17-3		0.21480163	g	275804	27.5804		206140	20.614
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.0005499	g	706	0.0706		527	0.0527
Pb Glass Fit Semiconductor Di	0.0086				7c4		g					
Pb Glass Fit Semiconductor Di		Lead/Lead Compounds	Lead (II) titanate	12060-00-3		0.00008928	g	10381	1.0381		85	0.0085
Pb Glass Fit Semiconductor Di		Glass	Fibrous-glass-wool	65907-17-3		0.00008551	g	9943	0.9943		82	0.0082
Pb Glass Fit Semiconductor Di		Solvents, additives, and other materials	2,2,4-trimethyl-1,3-pentanediol-1-monoisobutyrate	25265-77-4		0.00008551	g	9943	0.9943		82	0.0082
Pb Glass Fit Semiconductor Di		Glass	Silicon, doped	-		0.0083397	g	969733	96.9733		7999	0.7999
Gel Die Encapsulant	0.0277						g					
Gel Die Encapsulant		Solvents, additives, and other materials	Fluorosilicone monomer (fluorosilicone rubber)	2374-14-3		0.021606	g	780000	78		20725	2.0725
Gel Die Encapsulant		Plastics/polymers	Oxetane, 2,2,3,3-tetrafluoro-homopolymer, fluorinated	113114-19-5		0.006094	g	220000	22		5845	0.5845
Gel Die Encapsulant	0.0277						g					
Gel Die Encapsulant		Solvents, additives, and other materials	Fluorosilicone monomer (fluorosilicone rubber)	2374-14-3		0.021606	g	780000	78		20725	2.0725
Gel Die Encapsulant		Plastics/polymers	Oxetane, 2,2,3,3-tetrafluoro-homopolymer, fluorinated	113114-19-5		0.006094	g	220000	22		5845	0.5845
Bonding Wire	0.0011						g					
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0011	g	1000000	100		1055	0.1055
Cap/Cover	0.1958						g					
Cap/Cover		Metals	Chromium, metal	7440-47-3		0.03608007	g	184270	18.427		34609	3.4609
Cap/Cover		Metals	Copper, metal	7440-50-8		0.00049028	g	2504	0.2504		470	0.047
Cap/Cover		Solvents, additives, and other materials	Sulfur	7704-34-9		0.00000979	g	50	0.005		9	0.0009
Cap/Cover		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00003427	g	175	0.0175		32	0.0032
Cap/Cover		Solvents, additives, and other materials	Silicon	7440-21-0		0.00009037	g	5007	0.5007		940	0.094
Cap/Cover		Metals	Iron, metal	7439-89-6		0.13918971	g	710877	71.0877		133515	13.3515
Cap/Cover		Metals	Manganese, metal	7439-96-5		0.00225503	g	11517	1.1517		2163	0.2163
Cap/Cover		Nickel (external applications only)	Nickel	7440-02-0		0.01647128	g	84123	8.4123		15799	1.5799
Cap/Cover		Metals	Titanium, metal	7440-32-6		0.000196	g	1001	0.1001		188	0.0188
Cap/Cover		Solvents, additives, and other materials	Carbon	7440-44-0		0.0000932	g	476	0.0476		89	0.0089

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MPXAZ6115A6U_IPC1752_v11.xml

http://www.freescale.com/mcds/MPXAZ6115A6U_IPC1752A.xml